



PART NO. : TG1G-EX05J24LF

DESIGNED FOR DUAL-PORT FAST ETHERNET OR
SINGLE-PORT GIGABIT ETHERNET APPLICATIONS

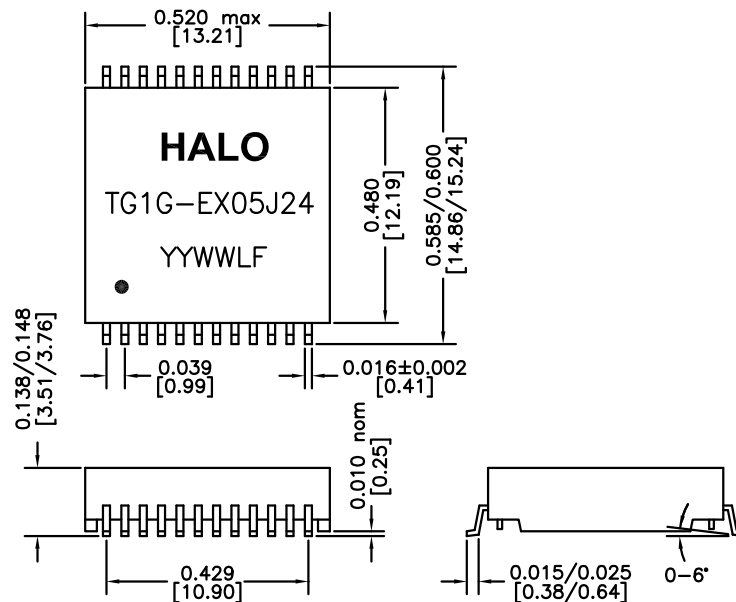
LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

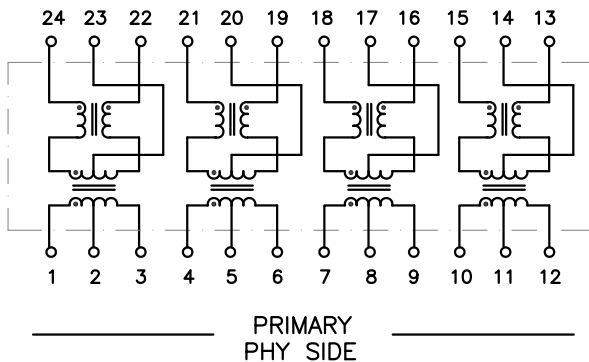
EXTENDED OPERATING TEMPERATURE $-40/+105^{\circ}\text{C}$

ELECTRICAL SPECIFICATIONS @ 25°C

URNS RATIO	1CT:1CT $\pm 3\%$
OCL (100KHz,0.1V,8mA)	350 μH min
DCR (PRI)	1.3 Ω max
LL (1MHz,0.1V)	0.4 μH max
Cw/w	30pF max
INSERTION LOSS 1-100MHz	-1.1dB max
RETURN LOSS 0.5-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CROSSTALK 1-100MHz	-40dB typ
CMR 1-100MHz	-40dB typ
ISOLATION	1,500Vrms



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ± 0.005 INCH IF NOT SPECIFIED

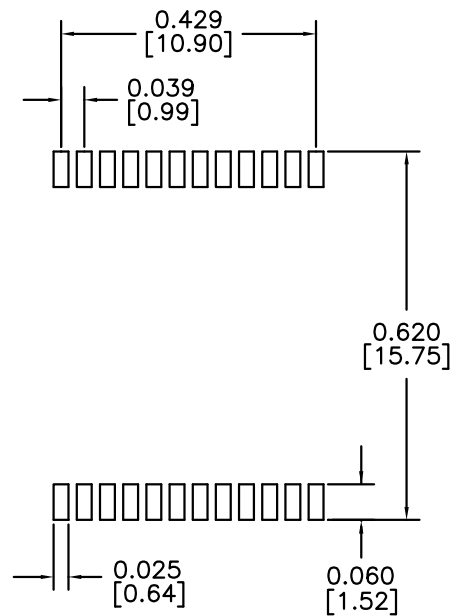


HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE		SIGNATURES		DATE	REV.	DESC.	DATE
FOR	ISOLATION MODULE	DRAWN	LI ZHI ZHONG	12/13/17	A	PROD. RELEASE	12/13/17
PART NO.	1000BASE-T, IEEE802.3ab	CHECKED	LEI KEONG	12/13/17			
	TG1G-EX05J24LF	APPROVED	PETER LU	12/13/17			
SCALE	NONE	PAGE	EX05J24LF.DWG				
	1 OF 2						

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RECOMMENDED PAD DIMENSIONS
DIMENSIONS: Inch [mm]

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CALIFORNIA, USA
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PART NO.	TG1G-EX05J24LF		CHECKED LEI KEONG	12/13/17			
SCALE	NONE	PAGE	2 OF 2	APPROVED PETER LU	12/13/17		
			FILE	EX05J24LF.DWG			